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**Izdelki iz polprevodniških čipov - 1. del: Zahteve za oskrbo in uporabo (IEC 62258-1:2005)**

**(istoveten EN 62258-1:2005)**

Semiconductor die products - Part 1: Requirements for procurement and use (IEC 62258-1:2005)

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EUROPEAN STANDARD

**EN 62258-1**

NORME EUROPÉENNE

EUROPÄISCHE NORM

November 2005

ICS 31.080.99

Supersedes ES 59008-1:1999 & ES 59008-2:1999 & ES 59008-3:1999

English version

**Semiconductor die products**  
**Part 1: Requirements for procurement and use**  
(IEC 62258-1:2005)

Produits de matrice de semi-conducteur  
Partie 1: Exigences pour l'acquisition  
et l'utilisation  
(CEI 62258-1:2005)

Halbleiter-Chip-Erzeugnisse  
Teil 1: Anforderungen für Beschaffung  
und Anwendung  
(IEC 62258-1:2005)

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This European Standard was approved by CENELEC on 2005-10-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

## Foreword

The text of document 47/1820/FDIS, future edition 1 of IEC 62258-1, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62258-1 on 2005-10-01.

This European Standard supersedes ES 59008-1:1999, ES 59008-2:1999 and ES 59008-3:1999.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2006-07-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2008-10-01

Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the International Standard IEC 62258-1:2005 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2	NOTE	Harmonized in EN 60068-2 series (not modified).
ISO 9000	NOTE	Harmonized as EN ISO 9000:2000 (not modified).
ISO 10303	NOTE	Harmonized in ENV ISO 10303 series (not modified).
IEC 61540	NOTE	Harmonized as HD 639 S1:2002 (modified).
ISO 8879	NOTE	Harmonized as EN 28879:1990 (not modified).
IEC 61340-5-1	NOTE	Harmonized as EN 61340-5-1:2001 (not modified).
IEC 61340-5-2	NOTE	Harmonized as EN 61340-5-2:2001 (not modified).

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**Annex ZA**  
(normative)

**Normative references to international publications  
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE Where an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-4	1999	Mechanical standardization of	EN 60191-4	1999
A1	2001	semiconductor devices	A1	2002
A2	2002	Part 4: Coding system and classification into forms of package outlines for semiconductor device packages	A2	2002
IEC 61360-1	2002	Standard data element types with associated classification scheme for electric components	EN 61360-1	2002
		Part 1: Definitions - Principles and methods		
IEC 62258-2	2005	Semiconductor die products Part 2: Exchange data formats	EN 62258-2	2005
ISO 14644-1	1999	Cleanrooms and associated controlled environments	EN ISO 14644-1	1999
		Part 1: Classification of air cleanliness		

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# INTERNATIONAL STANDARD

# IEC 62258-1

First edition  
2005-08

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## Semiconductor die products –

### Part 1: Requirements for procurement and use

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International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland  
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: [inmail@iec.ch](mailto:inmail@iec.ch) Web: [www.iec.ch](http://www.iec.ch)



Commission Electrotechnique Internationale  
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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## SEMICONDUCTOR DIE PRODUCTS –

## Part 1: Requirements for procurement and use

## FOREWORD

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International Standard IEC 62258-1 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1820/FDIS	47/1832/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

IEC 62258, as currently conceived, consists of the following parts, under the general title *Semiconductor die products*:

- Part 1: Requirements for procurement and use
- Part 2: Exchange data formats <sup>1</sup>
- Part 3: Recommendations for good practice in handling, packing and storage (Technical Report) <sup>1</sup>
- Part 4: Questionnaire for die users and suppliers (Technical Report) <sup>2</sup>
- Part 5: Requirements for information concerning electrical simulation <sup>2</sup>
- Part 6: Requirements for information concerning thermal simulation <sup>2</sup>

Further parts may be added as required.

A bilingual version of this publication may be issued at a later date.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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<sup>1</sup> To be published.

<sup>2</sup> In preparation.

## INTRODUCTION

This International Standard is based on the work carried out in the ESPRIT 4<sup>th</sup> Framework project GOOD-DIE which resulted in the publication of the ES59008 series of European specifications. Organizations that helped prepare this standard include the ESPRIT GOOD-DIE project, The Die Products Consortium, JEITA, JEDEC and ZVEI.

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